

SOT1313-1

plastic thermal enhanced low profile quad flat package: 208 leads

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HLQFP208
Package type industry code	HLQFP208
Package style descriptive code	HLQFP (thermal enhanced low profile quad flat package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	MS-026
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	4-11-2011

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	27.8	-	28	28.2	mm
E	package width	27.8	-	28	28.2	mm
A	seated height	1.4	-	1.5	1.6	mm
A ₂	package height	1.35	-	1.4	1.45	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	208	-	

2. Package outline

Fig. 1. Package outline HLQFP208 (SOT1313-1)



3. Legal information

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